

N&P-Channel V Complementary MOSFET

Description

The PT1ES uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

N channel

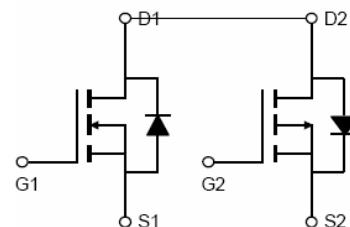
- $V_{DS} = 30V, I_D = 15A$
- $R_{DS(ON)} < 7m\Omega @ V_{GS}=10V$
- $R_{DS(ON)} < 12m\Omega @ V_{GS}=4.5V$

P channel

- $V_{DS} = -30V, I_D = -25A$
- $R_{DS(ON)} < 1m\Omega @ V_{GS}=-10V$
- $R_{DS(ON)} < 5m\Omega @ V_{GS}=-4.5V$
- High density cell design for ultra low $R_{DS(on)}$
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

- H-bridge
- Inverters



Schematic diagram



Marking and pin assignment

100% UIS TESTED!

100% ΔV_{ds} TESTED!

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
PT1ES	PT1ES	TO-252-4L	-	-	-

Absolute Maximum Ratings ($T_c=25^\circ C$ unless otherwise noted)

Parameter	Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage	V_{DS}	30	-30	V
Gate-Source Voltage	V_{GS}	± 20	± 20	V
Continuous Drain Current <small>$T_c=25^\circ C$</small>	I_D	15	-25	A
		24.5	-17.5	
Pulsed Drain Current <small>(Note 1)</small>	I_{DM}	105	-75	A
Maximum Power Dissipation <small>$T_c=25^\circ C$</small>	P_D	21		W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 175		°C

Thermal Characteristic

Thermal Resistance, Junction-to-Case <small>(Note 2)</small>	$R_{\theta JC}$	7	°C/W
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N-Channel Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	30	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.0	1.5	2.5	V
Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=7\text{A}$	-	5.5	7	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=6\text{A}$	-	7.8	12	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=7\text{A}$	-	29	-	S
Dynamic Characteristics (Note 4)						
Input Capacitance	C_{iss}	$V_{\text{DS}}=15\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	450	-	PF
Output Capacitance	C_{oss}		-	150	-	PF
Reverse Transfer Capacitance	C_{rss}		-	90	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=15\text{V}, R_{\text{L}}=2.5\Omega$ $V_{\text{GS}}=10\text{V}, R_{\text{G}}=3\Omega$	-	5	-	nS
Turn-on Rise Time	t_{r}		-	12	-	nS
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	19	-	nS
Turn-Off Fall Time	t_{f}		-	6	-	nS
Total Gate Charge	Q_{g}	$V_{\text{DS}}=15\text{V}, I_{\text{D}}=6\text{A}, V_{\text{GS}}=10\text{V}$	-	9.5	-	nC
Gate-Source Charge	Q_{gs}		-	2.0	-	nC
Gate-Drain Charge	Q_{gd}		-	1.9	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V_{SD}	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=35\text{A}$	-		1.2	V
Diode Forward Current (Note 2)	I_{S}		-	-	35	A

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production
5. EAS condition: $T_j=25^\circ\text{C}, V_{\text{DD}}=30\text{V}, V_{\text{G}}=10\text{V}, L=0.5\text{mH}, R_g=25\Omega$

N-Channel Typical Electrical and Thermal Characteristics (Curves)

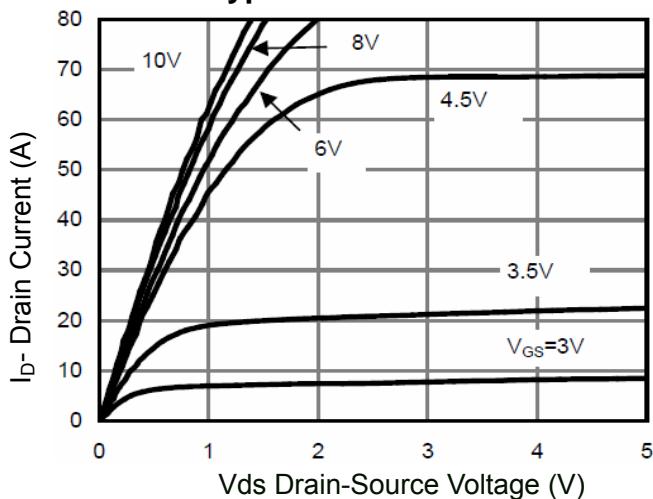


Figure 1 Output Characteristics

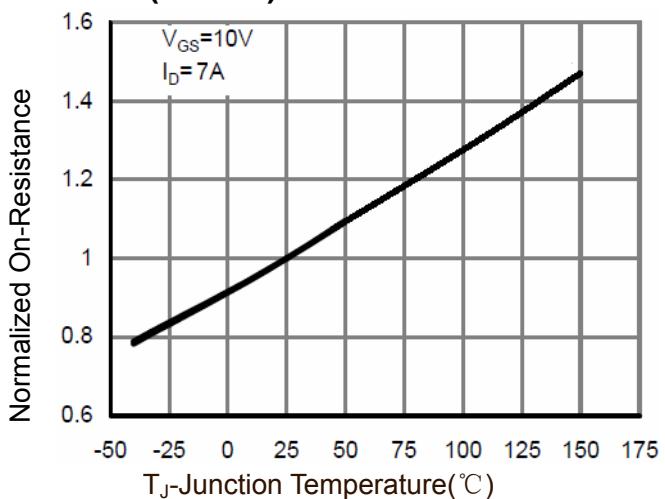


Figure 4 Rdson-Junction Temperature

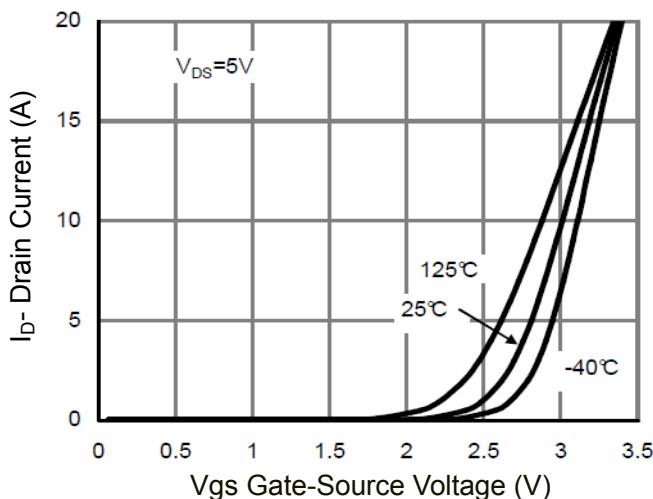


Figure 2 Transfer Characteristics

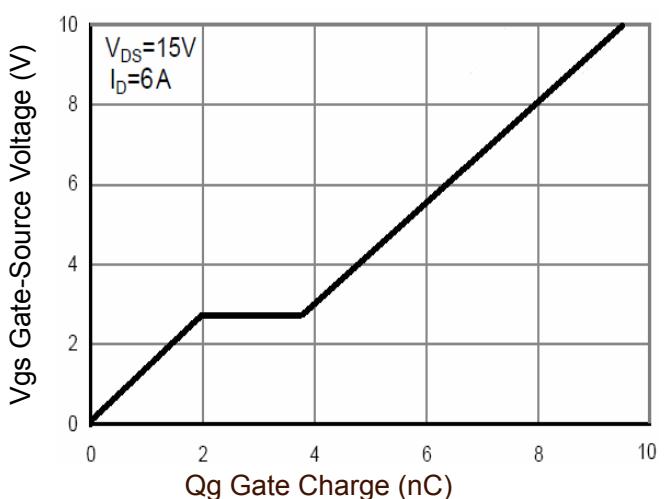


Figure 5 Gate Charge

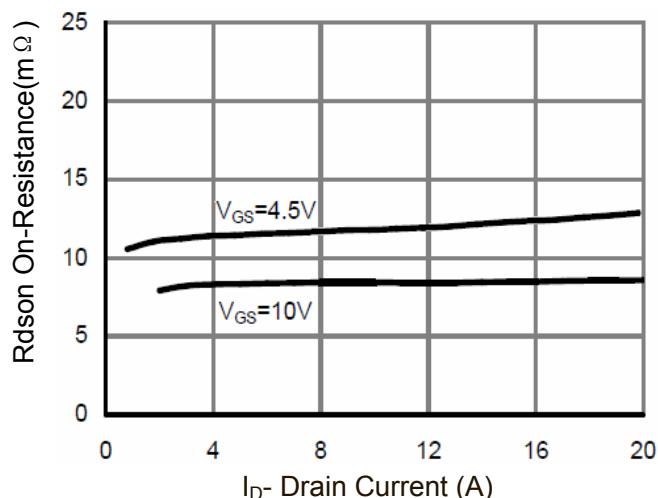


Figure 3 Rdson- Drain Current

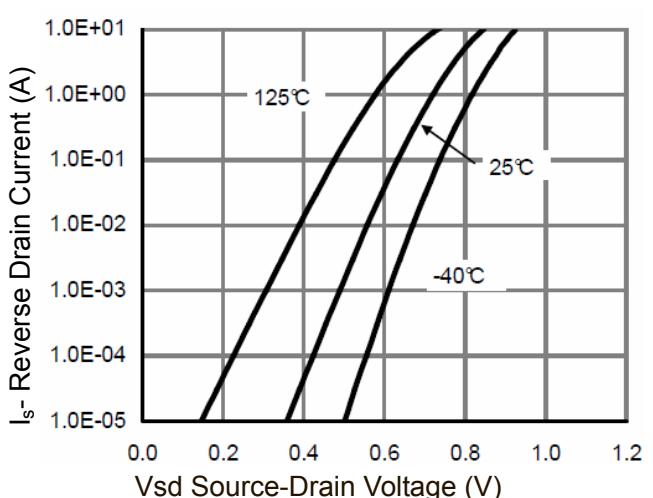


Figure 6 Source- Drain Diode Forward

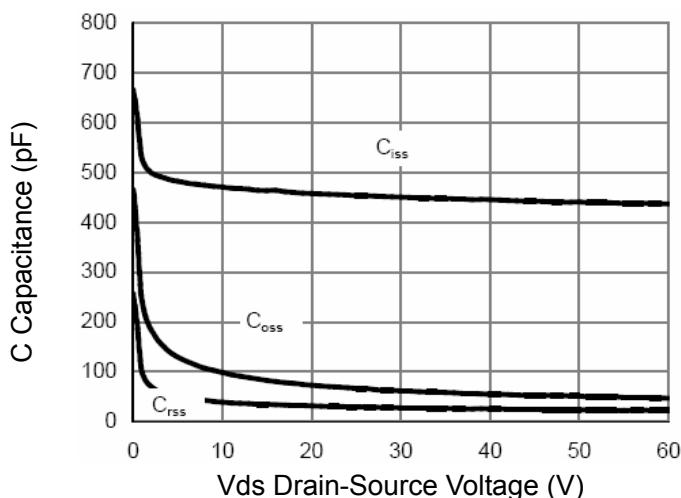


Figure 7 Capacitance vs Vds

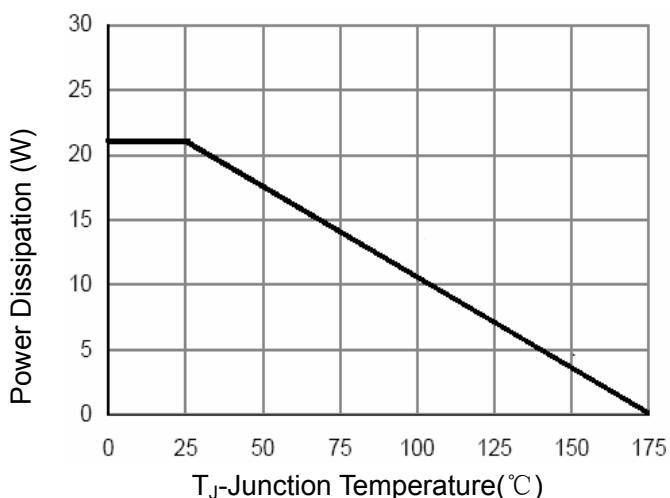


Figure 9 Figure 9 Power De-rating

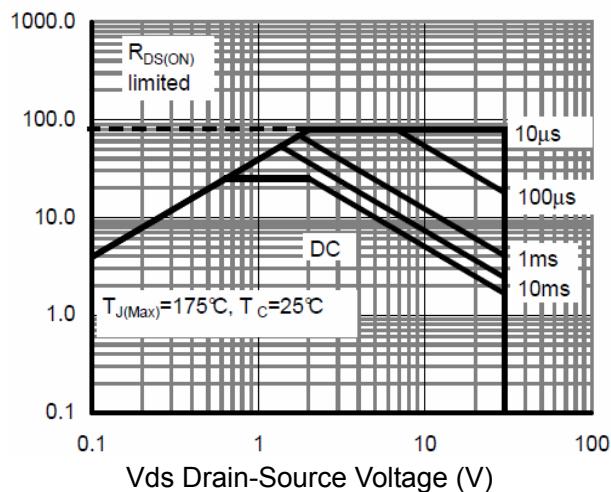


Figure 8 Safe Operation Area

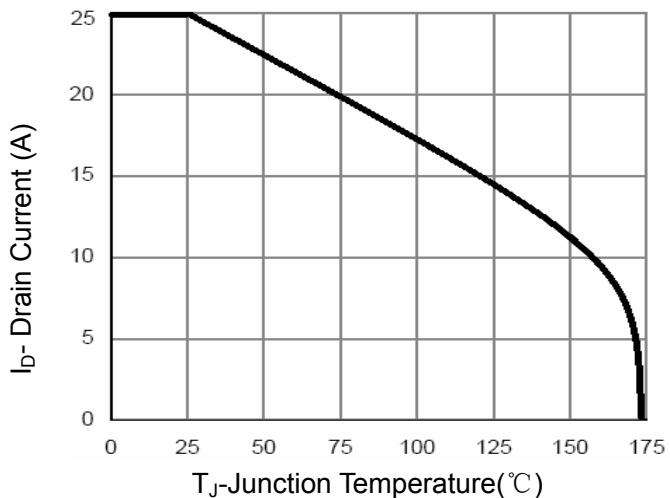
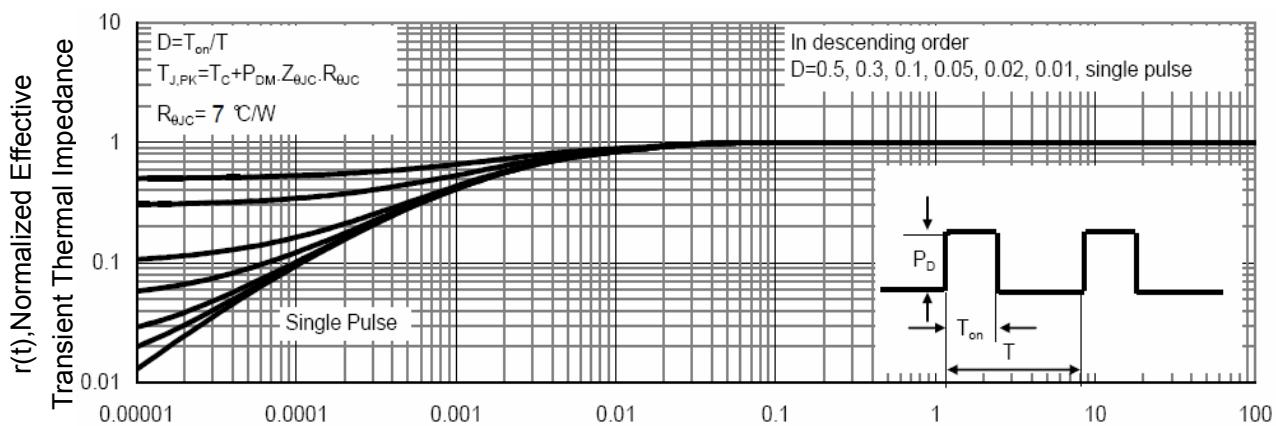


Figure 10 Current De-rating



Square Wave Pulse Duration(sec)
Figure 11 Normalized Maximum Transient Thermal Impedance

P-Channel Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-30	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=-30\text{V}, V_{\text{GS}}=0\text{V}$	-	-	-1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	±100	nA
On Characteristics <small>(Note 3)</small>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1.0	-1.5	-2.4	V
Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-6\text{A}$	-	15	18	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-5\text{A}$		20	25	
Forward Transconductance	g_{FS}	$V_{\text{DS}}=-5\text{V}, I_{\text{D}}=-6\text{A}$	-	15	-	S
Dynamic Characteristics <small>(Note 4)</small>						
Input Capacitance	C_{iss}	$V_{\text{DS}}=-30\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	920	-	PF
Output Capacitance	C_{oss}		-	140	-	PF
Reverse Transfer Capacitance	C_{rss}		-	90	-	PF
Switching Characteristics <small>(Note 4)</small>						
Turn-on Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}}=-15\text{V}, R_{\text{L}}=2.5\Omega$ $V_{\text{GS}}=-10\text{V}, R_{\text{G}}=3\Omega$	-	8	-	nS
Turn-on Rise Time	t_{r}		-	30	-	nS
Turn-Off Delay Time	$t_{\text{d(off)}}$		-	22	-	nS
Turn-Off Fall Time	t_{f}		-	26	-	nS
Total Gate Charge	Q_{g}	$V_{\text{DS}}=-15\text{V}, I_{\text{D}}=-6\text{A}, V_{\text{GS}}=-10\text{V}$	-	16.2	-	nC
Gate-Source Charge	Q_{gs}		-	2.9	-	nC
Gate-Drain Charge	Q_{gd}		-	3.6	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage <small>(Note 3)</small>	V_{SD}	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=-6\text{A}$	-		-1.2	V
Diode Forward Current <small>(Note 2)</small>	I_{S}		-	-	-25	A
Reverse Recovery Time	t_{rr}	$T_{\text{J}} = 25^\circ\text{C}, \text{IF} = -6\text{A}$ $dI/dt = 100\text{A}/\mu\text{s}$ <small>(Note 3)</small>	-	23	-	nS
Reverse Recovery Charge	Q_{rr}		-	14	-	nC

P-Channel Typical Electrical and Thermal Characteristics (Curves)

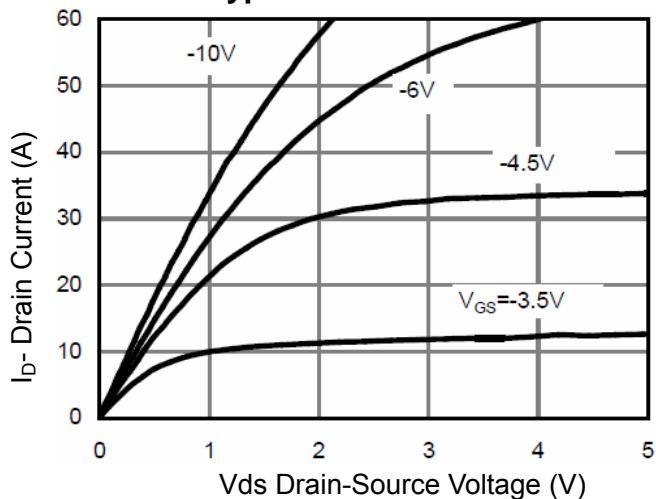


Figure 1 Output Characteristics

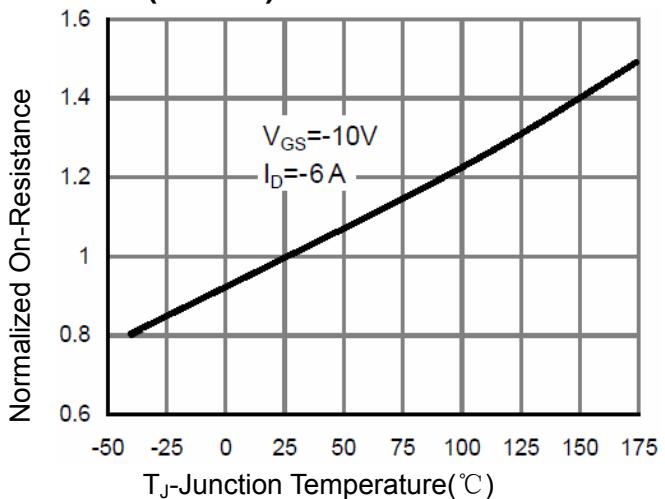


Figure 4 Rdson-Junction Temperature

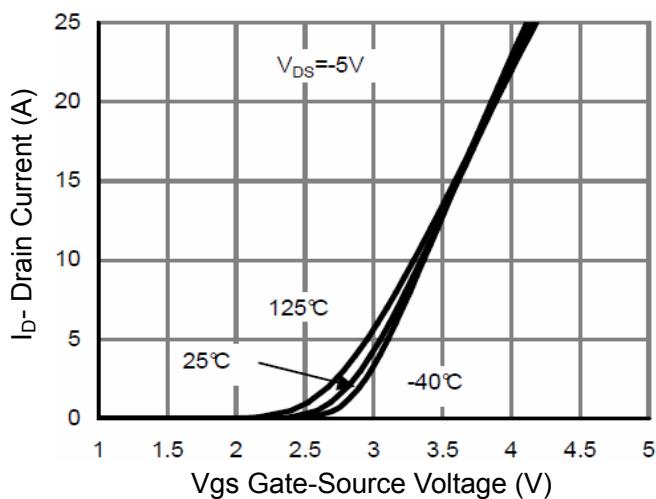


Figure 2 Transfer Characteristics

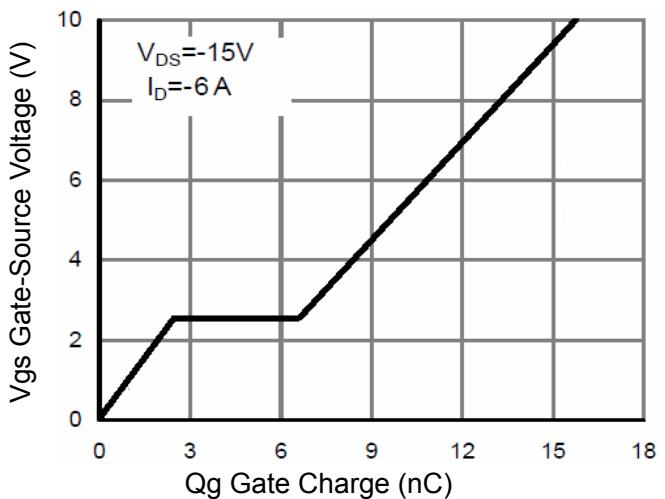


Figure 5 Gate Charge

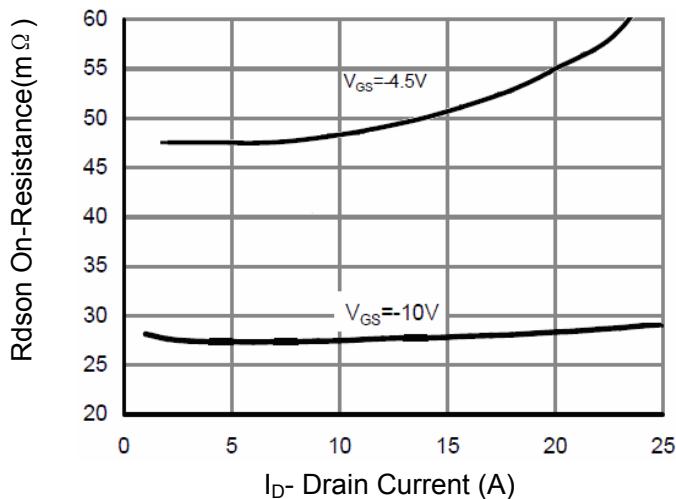


Figure 3 Rdson- Drain Current

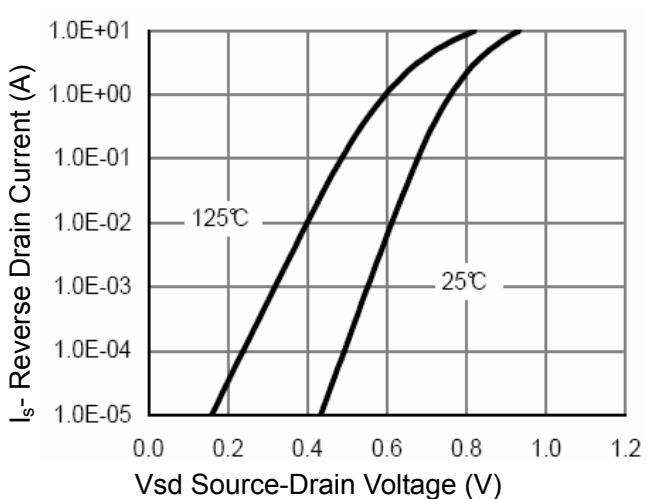


Figure 6 Source- Drain Diode Forward

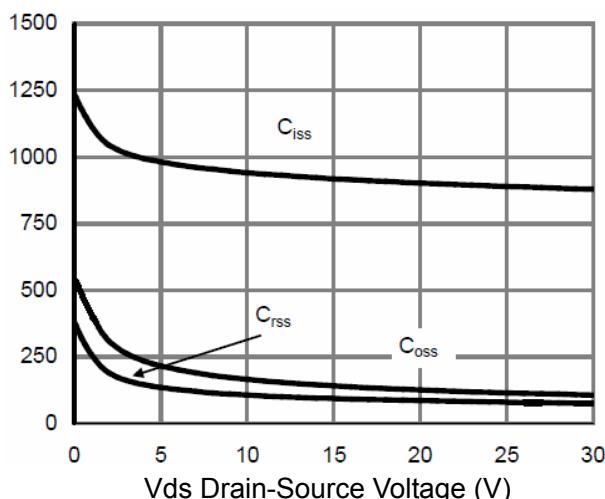


Figure 7 Capacitance vs Vds

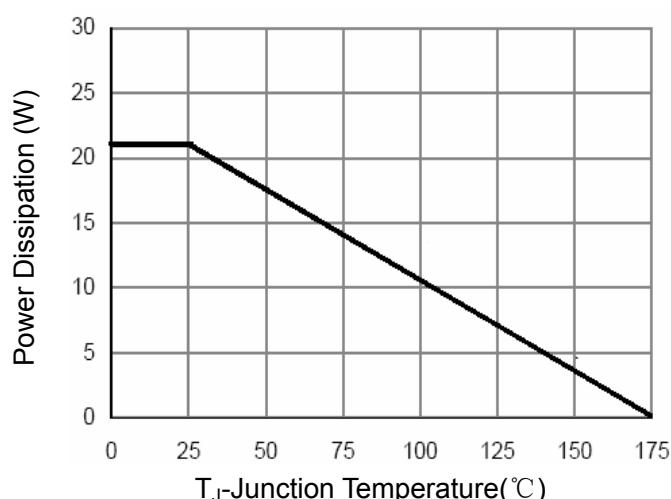


Figure 9 Power De-rating

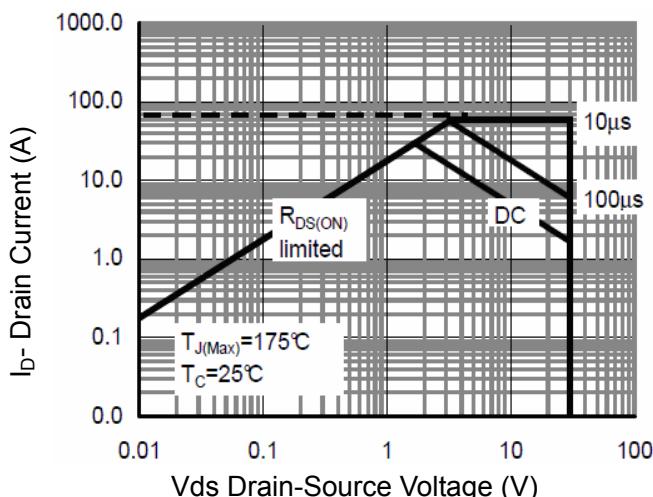


Figure 8 Safe Operation Area

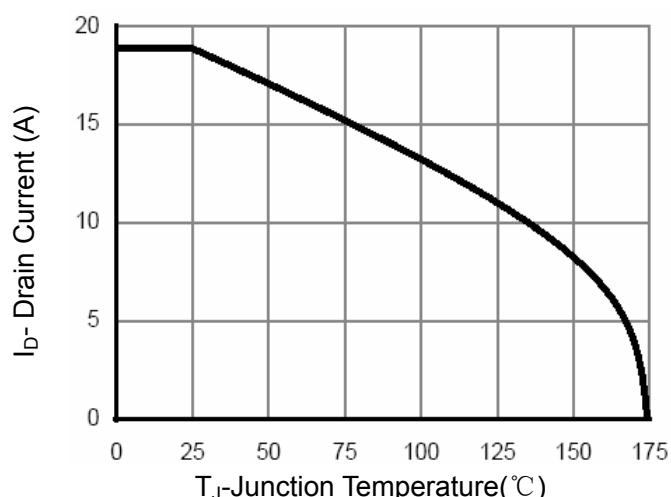


Figure 10 Current De-rating

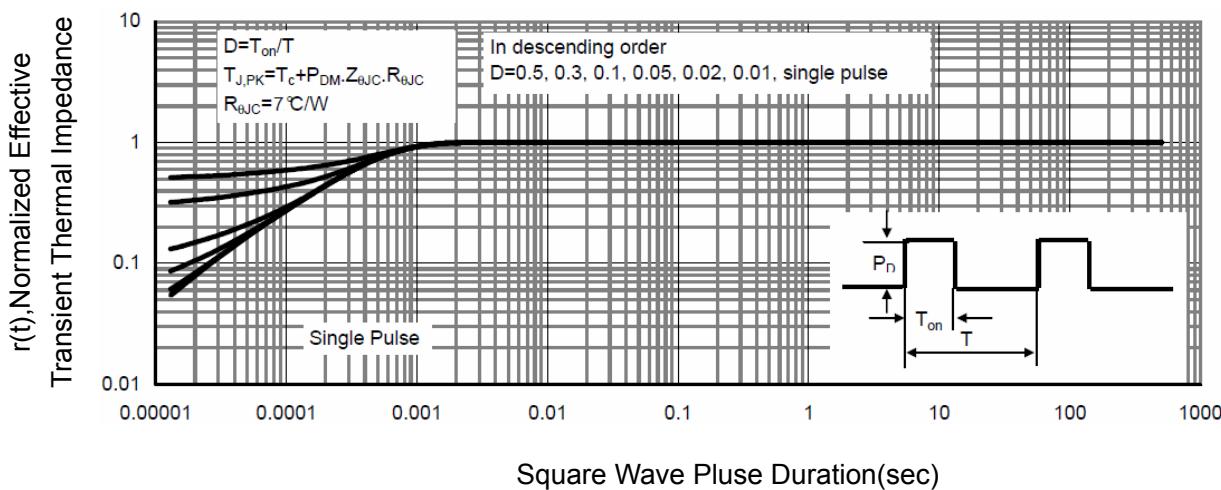
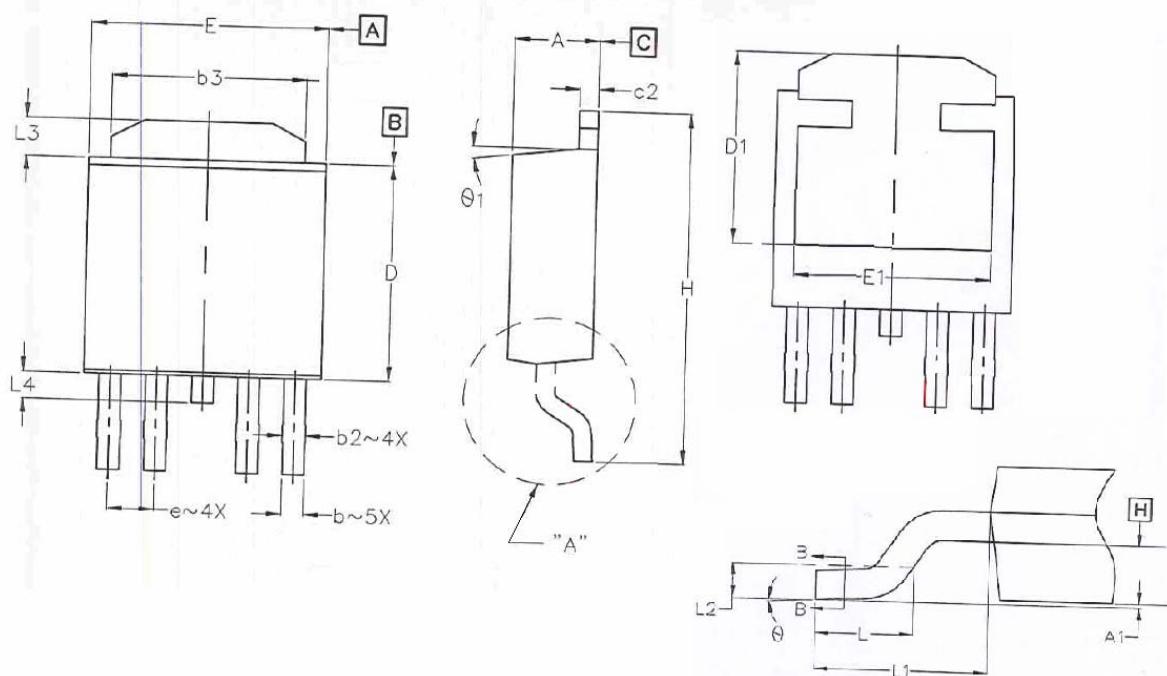


Figure 11 Normalized Maximum Transient Thermal Impedance

TO-252-4L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.184	2.387	0.086	0.094
A1	-	0.127	-	0.094
b	0.508	0.711	0.020	0.028
b1	0.508	0.660	0.020	0.026
b2	0.610	0.787	0.024	0.031
b3	4.953	5.461	0.195	0.215
c	0.460	0.610	0.018	0.024
c1	0.410	0.559	0.016	0.022
C2	0.460	12.950	0.498	0.510
D	4.980	5.180	0.196	0.204
D1	2.650	2.950	0.104	0.116
E	7.900	8.100	0.311	0.319
E1	0.000	0.300	0.000	0.012
e	12.900	13.400	0.508	0.528
H	2.850	3.250	0.112	0.128
L	1.397	1.778	0.055	0.070
L1	2.743	BSC	0.108	BSC
L2	0.508	BSC	0.020	BSC
L3	0.889	1.270	0.035	0.050
L4	-	1.015	-	0.040
θ	0°	10°	0°	10°
θ1	0°	15°	0°	15°